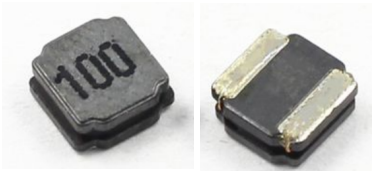
MetalLions

MNR6045 Series

Wire Wound SMD Power Inductors

FEATURES

- Magnetic-resin shielded construction reduces buzz noise to ultra-low levels
- Metallization on ferrite core results in excellent shock resistance and damage-free durability
- Closed magnetic circuit design reduces leakage flux and Electro Magnetic Interference (EMI)
- 30% higher current rating than conventional inductors of equal size
- Takes up less PCB real estate and save more power
- Operate temperature range .... −40℃～+125℃(Including self temp. rise)
- RoHS compliant



APPLICATIONS

- Smart phone, smart TV, set top box, notebook
- Car navigation systems, telecomm base stations
- VR, AR
- LED lighting

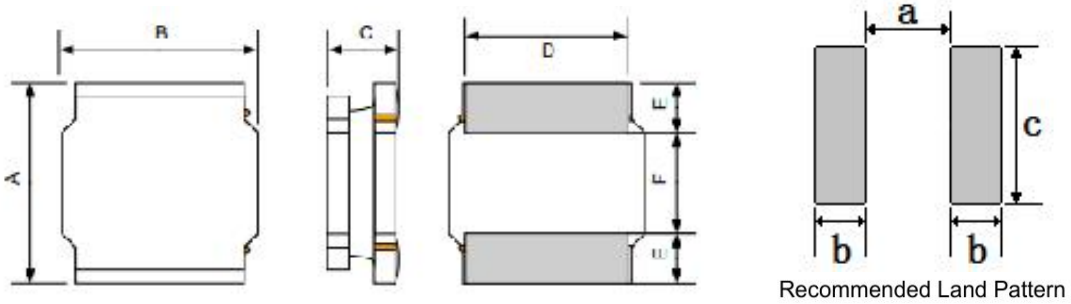
Explanation of Part Number

MNR 6045T 1R0 M T

1 2 3 4 5

- 1:Product Series:Wire Wound SMD Power Inductors
- 2:Dimensions:
- 3: Initial inductance value: 1R0 = 1.0uH
- 4:Tolerance of Inductance:M:±20%
- 5.Packing:Tape Carrier Package

Dimensions: [mm]



Recommended Land Pattern

Series	A	B	C	D	E	F	a Typ.	b Typ.	c Typ.
MNR6045	6.0±0.3	6.0±0.3	4.5 Max.	4.9±0.3	1.55±0.3	2.9±0.2	2.8	1.7	5.7

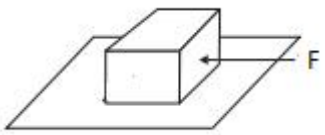
Electrical Characteristics List

Part Number	Inductance	DC Resistance		Isat(A)		Irms(A)		Marking
	100KHz/1.0V	Max.	Typ.	Max.	Typ.	Max.	Typ.	
Units	（uH）	Ω	Ω	A	A	A	A	
MNR6045T1R0MT	1.0±20%	0.014	0.011	9.50	10.00	5.50	6.00	1R0
MNR6045T1R5MT	1.5±20%	0.016	0.013	8.80	9.50	4.95	5.40	1R5
MNR6045T2R2MT	2.2±20%	0.023	0.018	6.75	7.40	4.60	5.00	2R2
MNR6045T3R3MT	3.3±20%	0.027	0.022	5.90	6.20	3.70	4.00	3R3
MNR6045T4R7MT	4.7±20%	0.034	0.027	4.97	5.50	3.30	3.60	4R7
MNR6045T5R6MT	5.6±20%	0.038	0.032	4.15	4.60	3.15	3.40	5R6
MNR6045T6R8MT	6.8±20%	0.040	0.035	3.90	4.30	3.00	3.30	6R8
MNR6045T8R2MT	8.2±20%	0.060	0.053	3.90	4.30	2.60	2.80	8R2
MNR6045T100MT	10.0±20%	0.062	0.051	3.20	3.50	2.45	2.70	100
MNR6045T150MT	15.0±20%	0.088	0.073	2.50	2.70	2.05	2.20	150
SFE6045T220MT	22.0±20%	0.116	0.095	2.05	2.20	1.80	2.00	220
MNR6045T330MT	33.0±20%	0.178	0.158	1.65	1.80	1.45	1.60	330
MNR6045T470MT	47.0±20%	0.260	0.230	1.40	1.50	1.30	1.40	470
MNR6045T560MT	56.0±20%	0.287	0.254	1.30	1.40	1.10	1.20	560
MNR6045T680MT	68.0±20%	0.376	0.340	1.20	1.30	1.00	1.10	680
MNR6045T820MT	82.0±20%	0.500	0.430	1.00	1.10	1.00	1.10	820
MNR6045T101MT	100.0±20%	0.563	0.510	0.95	1.00	0.80	0.88	101
MNR6045T151MT	150.0±20%	0.754	0.690	0.80	0.88	0.70	0.77	151
MNR6045T221MT	220.0±20%	1.084	0.900	0.70	0.75	0.57	0.60	221
MNR6045T331MT	330.0±20%	1.651	1.530	0.57	0.60	0.55	0.57	331
MNR6045T471MT	470.0±20%	2.340	2.150	0.45	0.48	0.40	0.42	471
MNR6045T681MT	680.0±20%	3.250	2.900	0.40	0.42	0.33	0.35	681

※1: All test data is referenced to 20°C ambient;

※2: Rated current: Isat or Irms, whichever is smaller;
※*3: Isat: DC current at which the inductance drops approximate 30% from its value without current;
※*4: Irms: DC current that causes the temperature rise (△T =40°C) from 20°C ambient.

RELIABILITY TEST

No.	TEST ITEM	SPECIFICATION	TEST CONDITION
1	High temperature Storage test	1. No significant defects in appearance. 2.ΔL/L ≦ 10% 3.ΔDCR/DCR ≦ 10%	Temperature: 125℃±5℃ (N: Follow the product specification for the setting.) Time : 96±2 hours Place the samples for one hour at room temperature and test them within two hours
2	Low temperature Storage test	1. No significant defects in appearance. 2.ΔL/L ≦ 10% 3.ΔDCR/DCR ≦ 10%	Temperature: -40℃±5℃ (M: Follow the product specification for the setting) Time : 96±2 hours Place the samples for one hour at room temperature and test them within two hours.
3	Humidity test	1. No significant defects in appearance. 2.ΔL/L ≦ 10% 3.ΔDCR/DCR ≦ 10%	Temperature: 40±2℃ , Humidity: 93±3%RH Time : 96±2 hours Place the samples for one hour at room temperature and test them within two hours
4	Solderability test	Terminals must have 95% minimum solder coverage	1.Dip pads in flux then dip in solder pot at 245±5°C for 5 second. 2.Solder: lead free 3.Flux: rosin flux
5	Heat endurance of flow soldering	1. No significant defects in appearance. 2.ΔL/L ≦ 10% 3.ΔDCR/DCR ≦ 10%	1.Refer to the above reflow curve and go through the reflow for twice. 2.The peak temperature : 260+0/-5℃
6	Vibration test	1.No significant defects in appearance. 2.No short and no open.	Apply frequency 10~55~10Hz and amplitude 1.5mm, 1 min/cycle in X ㄱY and Z direction for 2 hours each. (total 6 hours)
7	Terminal strength push test	1. Applied force:10N Duration: 10sec 2.Solder paste thickness:0.12mm 3.Meet the above requirements without any loose termina	Solder the test samples to the PCB through245 ℃ reflow, apply a standard force on the side of the test samples for 10 seconds. 

We have suggested the storage period of lead-free product should not over 6 months.

SOLDERING CONDITIONS

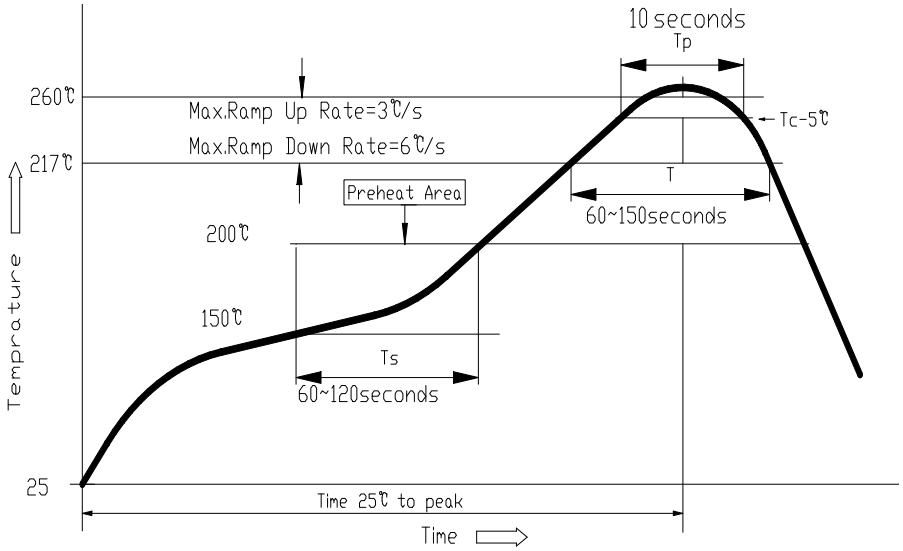
Applicable soldering process to the products is refl.

1 Soldering Materials

(1) Solder:Sn-3.0Ag-0.5Cu

(2) Flux:Use rosin-based flux,but not strongly acidic flux (with xhlorine exceeding 0.2wt%).Do not use water-soluble flux.

2 Reflow Soldering Profile



3 Soldering Iron

Reworking with electric solding iron must preheating at 150℃ for 1 minute is required,and do not directly touch the core with the tip of the soldering iron.The reworking soldering conditions are as follows.

①Temperature of soldering iron tip:350℃;

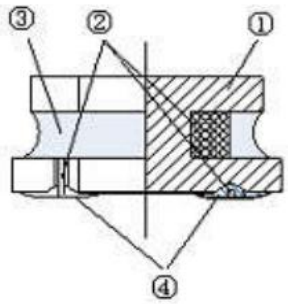
② Soldering iron power output:≤30W;

③ Diameter of soldering iron end:≤1.0mm;

④Soldering time:＜3 s



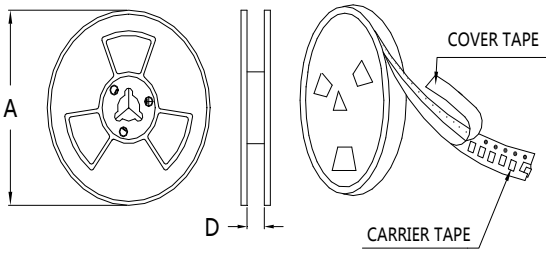
Structure (The structure of product.)



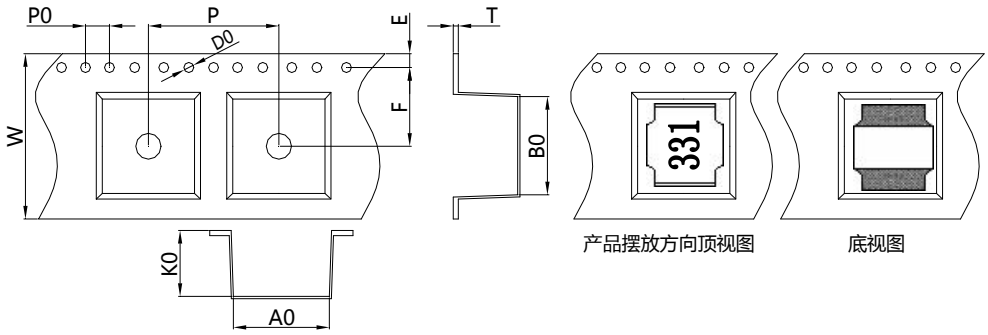
NO	Components	Material
①	Core	Ni-Zn Ferrite
②	Wire	Polyurethane system enameled copper wire
③	Magnetic Glue	Epoxy resin and magnetic powder
④	Plating	AgNiSn or FeNiCu + Sn Alloy

PACKAGING(unit: mm)

☑ 13″ 盘 ☐ 7″ 盘



	13″ 盘	7″ 盘
A	Φ330±2.0	Φ178±2.0
D	12.5	



Size	Item	W	A0	B0	K0	P	T	E	F	D0	P0
6045	(mm)	12.0±0.3	6.5±0.15	6.5±0.15	4.7±0.2	8.0±0.3	0.4±0.1	1.75±0.1	5.5±0.1	1.5±0.1	4.0±0.1

Quantity: 1500PCS/Reel